

# W396

Product Change Notification - LIAL-13OKM\

22 May 2020

**Product Category:** 

Memory

Date:

**Affected CPNs:** 



#### **Notification subject:**

CCB 2716.003 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel AT21CS01 and AT21CS11 devices families available in 3L SOT-23 (1.3mm) package.

**Notification text:** 

#### **PCN Status:**

Final notification.

## PCN Type:

Manufacturing Change

## **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MTAI as a new assembly site for selected Atmel AT21CS01 and AT21CS11 devices families available in 3L SOT-23 (1.3mm) package.

## Pre Change:

Assembled at ANAP using PdCu wire, 8290 die attach and G700LS mold compound

## **Post Change:**

Assembled at MTAI using Au wire, 8390A die attach and G600V mold compound material.

**Pre and Post Change Summary:** 

	Pre Change	Post Change			
	Amkor Technology	Microchip Technology			
Assembly Site	Philippine (P1/P2), INC.	Thailand (HQ)			
	(ANAP)	MTAI			
Wire material	PdCu	Au			
Die attach material	8290	8390A			
Molding compound	G700LS	G600V			
material	G700L3	G000V			
Lead frame material	C194	C194			

#### Impacts to Data Sheet:

Yes, POD (package outline drawing) change.

## **Change Impact:**



None

## **Reason for Change:**

To improve on-time delivery performance by qualifying MTAI as a new assembly site

#### **Change Implementation Status:**

In Progress

## **Estimated First Ship Date:**

June 22, 2020 (date code: 2026)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

#### **Time Table Summary:**

	May 2020				June 2020					
Workweek	18	19	20	21	22	23	24	25	26	27
Qual Report Availability					X					
Final PCN Issue Date					X					
Estimated Implementation Date									X	

#### **Method to Identify Change:**

Traceability code

#### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

## **Revision History:**

**May 22, 2020:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 22, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachment(s):

PCN\_LIAL-13OKMW396\_Qual report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

#### Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

LIAL-13OKMW396 - CCB 2716.003 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel AT21CS01 and AT21CS11 devices families available in 3L SOT-23 (1.3mm) package.

## Affected Catalog Part Numbers (CPN)

AT21CS01-STUM10-T

AT21CS01-STUM11-T

AT21CS01-STUM12-T

AT21CS01-STUM13-T

AT21CS01-STUM14-T

AT21CS01-STUM15-T

AT21CS01-STUM16-T

AT21CS01-STUM17-T

AT21CS01-STUMJK-T

AT21CS11-STU10-T

Date: Thursday, May 21, 2020